AMENDMENTS TO THE SPECIFICATION:

Please replace the paragraph beginning at page 5, line 1 with the following amended paragraph:

As shown in FIG. 4 ~~figure 4~~(seen from the top) and FIG. 5 ~~figure 5~~(seen from the bottom), some implementations of the rigid coupler may include a core 80 formed of a rigid epoxy laminated glass cloth sheet, such as grade FR4. (FIGS. 4 and 5 ~~figures 5 and 6~~ show only a portion of the full width of the rigid coupler. FIG. 5 ~~Figure 6~~ does not show the detail of the layers of the coupler.) The upper and lower faces of the rigid coupler may bear metalization layers 73, 75. The lower metalization layer 75 may bear the electromagnetic coupler traces 97, 99, 101 of the electromagnetic coupler (as seen in ~~figure 5~~ FIG. 5). The lower metalization layer may be mechanically coupled to, but electrically isolated from, the upper metalization layer by through vias 79, 81 that form conductive electrical links to solder pads 83, 85 that are formed in the upper metalization layer (but not in contact with the rest of the upper metalization layer).

Please replace the paragraph beginning at page 7, line 14 with the following amended paragraph:

In use, the digital device may be repeatedly inserted in and removed from the socket. Once inserted the signals can pass across the electromagnetically ~~electrometrically~~ coupled interface.

Please replace the paragraph beginning at page 9, line 12 with the following amended paragraph:

Each component 124, 134, and 144 ~~122, 132, and 142~~ may comprise any suitable circuitry. Each component 124, 134, and 144 ~~122, 132, and 142~~ for one embodiment serves as an interface for each device 120, 130, and 140 to communicate with device 110.